

**FLEX CIRCUIT ASSEMBLY WITH AN INTEGRATED CIRCUIT DEVICE
ATTACHED TO A BASE FILM WITH AN UNDERFILL PORTION AND
SEALED WITH A GLOB TOP PORTION**

ABSTRACT OF THE DISCLOSURE

[0040] A flex circuit assembly includes a flex circuit base film. The flex circuit assembly includes an integrated circuit device disposed adjacent the flex circuit base film and including a solder bump connection. The flex circuit assembly includes an electrically conductive trace disposed upon the base film. The trace includes a contact pad. The contact pad is electrically connected to the solder bump connection. The flex circuit assembly includes an underfill portion disposed between the base film and the integrated circuit device for attaching the integrated circuit device to the base film. The underfill portion is formed of an underfill material. The flex circuit assembly includes a glob top portion material disposed upon the underfill portion and the base film for sealing the electrically conductive trace. The glob top portion is formed of a glob top material. The glob top material is different than the underfill material.